



Click [here](#) for the 3D model.

| Dimensions | |
|------------|-----------------|
| L | 5.7mm +/-0.4mm |
| W | 5mm +/-0.4mm |
| T | 5.1mm +/-0.4mm |
| B | 0.6mm +/-0.35mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 300 |

| General Information | |
|---------------------|---|
| Series | KONNEKT Comm COG |
| Style | KONNEKT |
| Description | SMD, MLCC, KONNEKT, Ultra-Stable, Class I |
| Features | High Density Packaging |
| RoHS | Yes |
| Termination | Tin |
| AEC-Q200 | No |
| Component Weight | 645 mg |
| Chip Size | 2220-2 |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|---------------------|
| Capacitance | 7800 pF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 10% |
| Voltage DC | 2000 VDC |
| Dielectric Withstanding Voltage | 2400 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C |
| Dissipation Factor | 0.1% 1kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

单击下面可查看定价，库存，交付和生命周期等信息

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